IN THE CLAIMS

Please cancel claims 7, 9 and 11 without prejudice or disclaimer.

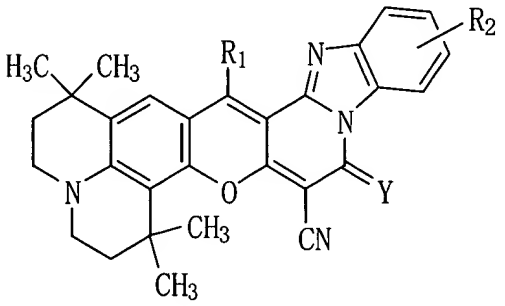
Please amend claims 1 and 12 as follows:

Claim 1 (Currently Amended): ~~A~~ An aqueous positive photosensitive resin composition comprising:

(A) a positive photosensitive resin component which is a carboxyl- and/or hydroxyphenyl-containing resin (a) in combination with an ether linkage-containing olefinic unsaturated compound (b),

(B) a photoacid generator which is a sulfonic acid ester and/or a sulfonic acid imide ester, ~~and~~

(C) a photosensitizer which is a benzopyran condensed ring compound capable of increasing photosensitivity to visible light with a wavelength of 480 nm or more and is represented by Formula (1)



(1)

wherein R_1 is hydrogen, halogen, cyano, trifluoromethyl, carboxyl or carboxylic acid ester, R_2 is hydrogen, alkyl, alkoxy, cyano, trifluoromethyl, sulfoxy or halogen, and Y is NH or O, and

(D) a photoacid proliferating agent which is an organic acid ester.

Claims 2 - 4 (Cancelled).

Claim 5 (Previously Presented): A composition according to claim 1, wherein the proportion of the unsaturated compound (b) is about 5 to 150 parts by weight per 100 parts by weight of the resin (a).

Claim 6 (Original): A composition according to claim 1, wherein the proportion of the photoacid generator (B) is about 0.1 to 40 parts by weight per 100 parts by weight of the resin (A).

Claim 7 (Cancelled).

Claim 8 (Original): A composition according to claim 1, wherein the proportion of the photosensitizer (C) is about 0.1 to 10 parts by weight per 100 parts by weight of the total amount of the resin (A) and photoacid generator (B).

Claim 9 (Cancelled).

Claim 10 (Original): A composition according to claim 1, which is an organic solvent-based resin composition.

Claim 11 (Cancelled).

Claim 12 (Currently Amended): A positive photosensitive dry film prepared by applying ~~a~~ an aqueous positive photosensitive resin composition according to claim 1 to a surface of support film, followed by drying, to thereby form a positive photosensitive resin layer.

Claim 13 (Original): A method of forming a pattern comprising the steps of:

(1) applying a positive photosensitive resin composition according to claim 1 to a substrate, followed by drying, to form a positive photosensitive resin coating,

(2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and

(3) removing the irradiated part of the positive photosensitive resin coating by development to form a resist pattern coating.

Claim 14 (Original): A method of forming a pattern comprising the steps of:

(1') attaching a positive photosensitive dry film according to claim 12 to a substrate so that the

photosensitive resin layer of the dry film is in contact with the substrate to form a positive photosensitive resin coating, and optionally peeling off the support film of the dry film,

(2) irradiating the resin coating with visible light directly or through a mask so as to obtain a desired pattern, and

(3') peeling off the support film of the dry film when the support film has not been peeled off, and removing the irradiated part of the positive photosensitive resin coating by development to form a resist pattern coating.